

N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- ☒ Surface-mounted package
- ☒ Advanced trench cell design

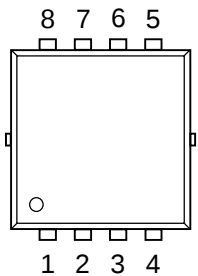
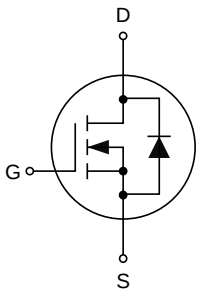
1.2 Applications

- ☒ Portable appliances
- ☒ Battery management
- ☒ High speed switch
- ☒ Low power DC/DC Converter

1.3 Quick reference

- ☒ $BV \geq 60V$
- ☒ $R_{DS(ON)} \leq 7.5m\Omega @ V_{GS} = 10V$
- ☒ $P_{tot} \leq 43W$
- ☒ $R_{DS(ON)} \leq 9.5m\Omega @ V_{GS} = 4.5V$
- ☒ $I_D \leq 55A$

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1,2,3	Source	 Top View PDFN3.3x3.3-8L	
4	Gate		
5,6,7,8	Drain		

3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_C=25^{\circ}\text{C}$	-	60	V
V_{GS}	Gate-Source Voltage	$T_C=25^{\circ}\text{C}$	-	± 20	V
I_D^*	Drain Current	$T_C=25^{\circ}\text{C}, V_{GS}=10\text{V}$	-	55	A
		$T_C=100^{\circ}\text{C}, V_{GS}=10\text{V}$	-	34.9	A
$I_{DM}^{*,**,***}$	Pulsed Source Current	$T_C=25^{\circ}\text{C}, V_{GS}=10\text{V}$	-	160	A
P_{tot}^*	Total Power Dissipation	$T_C=25^{\circ}\text{C}$	-	43	W
T_{stg}	Storage Temperature		-55	150	$^{\circ}\text{C}$
T_J	Junction Temperature		-	150	$^{\circ}\text{C}$
I_S	Diode Forward Current	$T_C=25^{\circ}\text{C}$	-	160	A
$R_{\theta JC}^*$	Thermal Resistance-Junction to Case		-	2.9	

Notes:

- * Surface Mounted on 1 in² pad area, $t \leq 10$ sec
- ** Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- *** Limited by bonding wire

4. Marking Information

Product Name	Marking
KJ0906QL	0906 YWWXXX YWWXXX: Date Code

5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ0906QL	PDFN3.3x3.3-8L	-	-	5000	

Note: KUAJIEXIN defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C)

6. Electrical Characteristics (T_A=25°C Unless Otherwise Noted)

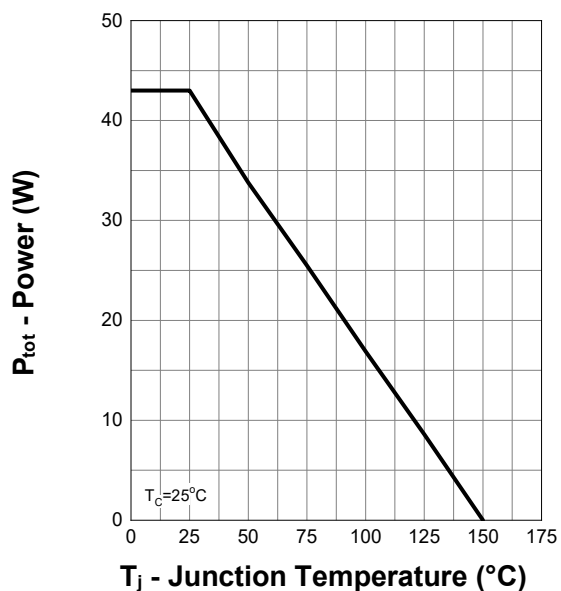
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	60	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1.0	-	2.0	V
I _{DSS}	Zero Gate Voltage Source Current	V _{DS} =48V, V _{GS} =0V	-	-	1	μA
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^a	Drain-Source On-State Resistance	V _{GS} =10V, I _{DS} =20A	-	6.5	7.5	mΩ
	Drain-Source On-State Resistance	V _{GS} =4.5V, I _{DS} =10A	-	8.8	9.5	mΩ
Diode Characteristics						
V _{SD} ^a	Diode Forward Voltage	I _{SD} =20A, V _{GS} =0V	-	-	1.3	V
t _{rr}	Reverse Recovery Time	I _{SD} =20A, dI _{SD} /dt=100A/μs	-	29	-	ns
Q _{rr}	Reverse Recovery Charge		-	12	-	nC
Dynamic Characteristics ^b						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, Frequency=1MHz	-	1500	-	pF
C _{oss}	Output Capacitance		-	488	-	
C _{rss}	Reverse Transfer Capacitance		-	60	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} =30V, V _{GEN} =10V, R _G =3.9Ω, R _L =4.5Ω, I _{DS} =20A	-	7.5	-	ns
t _r	Turn-on Rise Time		-	29	-	
t _{d(off)}	Turn-off Delay Time		-	24	-	
t _f	Turn-off Fall Time		-	22	-	
Gate Charge Characteristics ^b						
Q _g	Total Gate Charge	V _{DS} =30V, V _{GS} =10V, I _{DS} =20A	-	29	-	nC
Q _{gs}	Gate-Source Charge		-	6.5	-	
Q _{gd}	Gate-Drain Charge		-	4.8	-	

Notes:

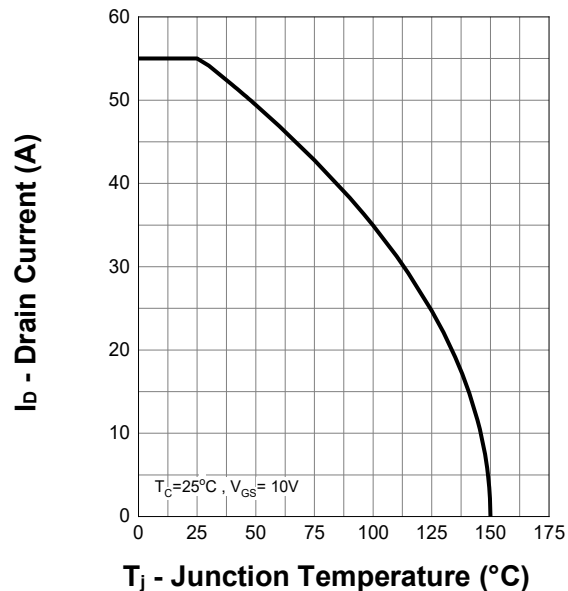
- Pulse test; pulse width ≤ 300μs, duty cycle ≤ 2%
- Guaranteed by design, not subject to production testing

7. Typical Characteristics

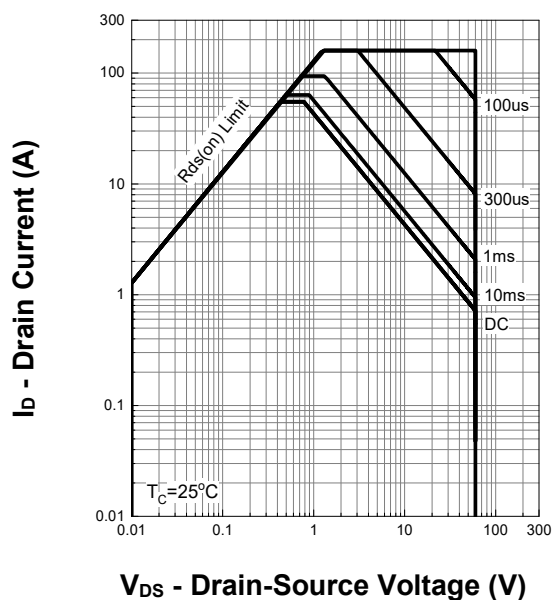
Power Capability



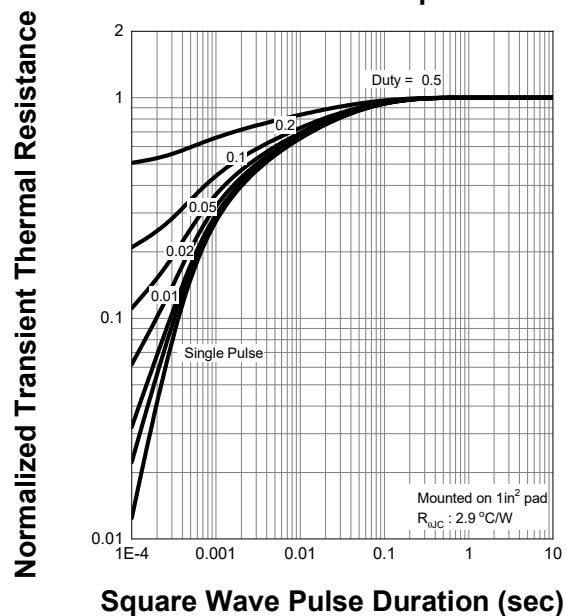
Current Capability



Safe Operating Area

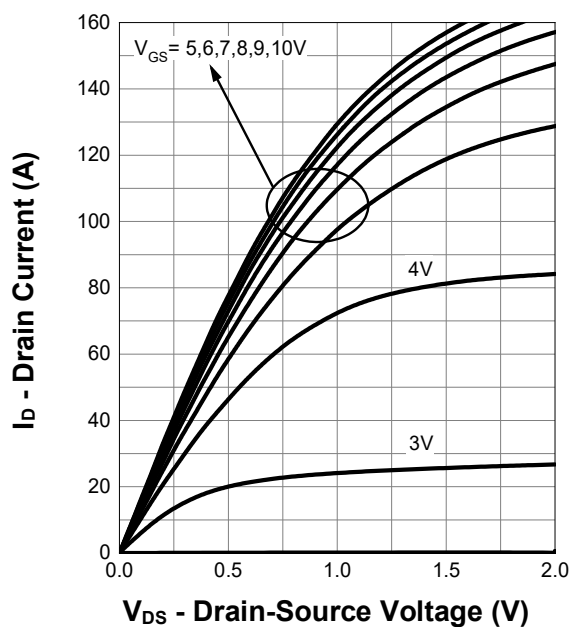


Transient Thermal Impedance

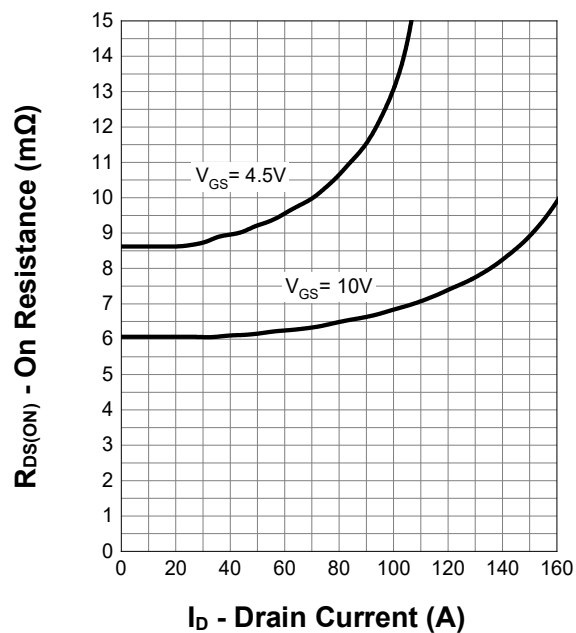


7. Typical Characteristics (Cont.)

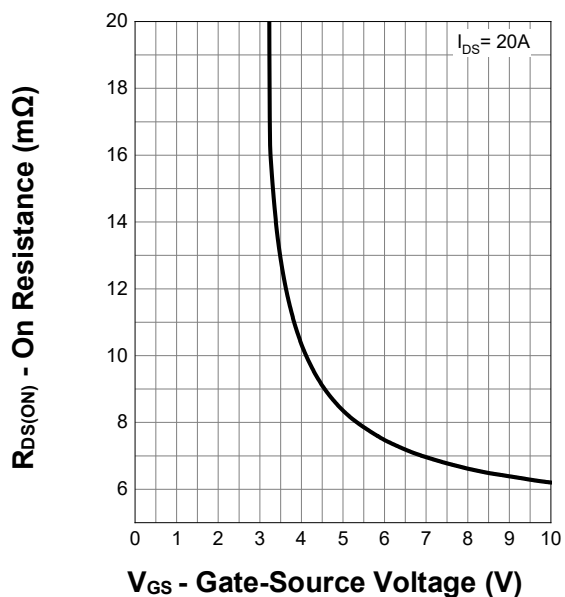
Output Characteristics



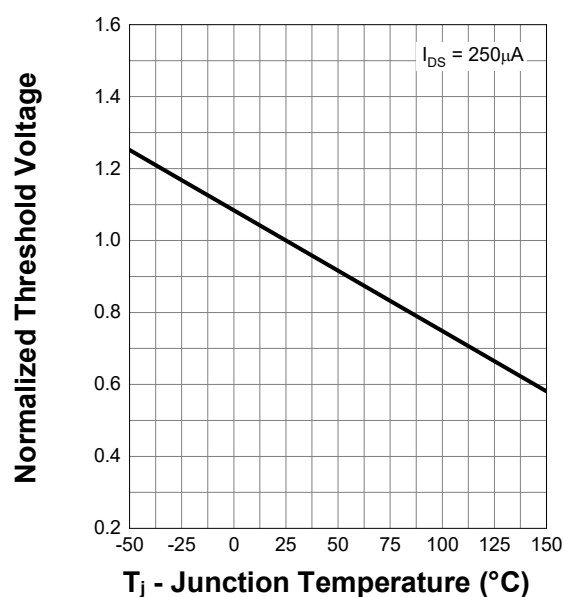
On Resistance



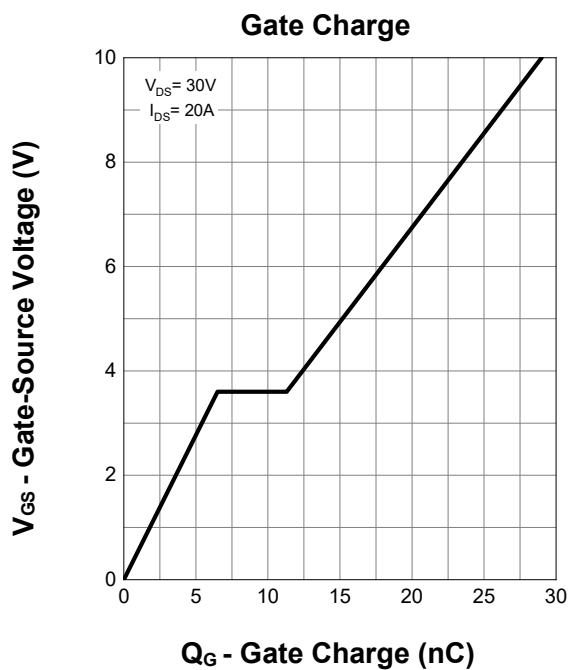
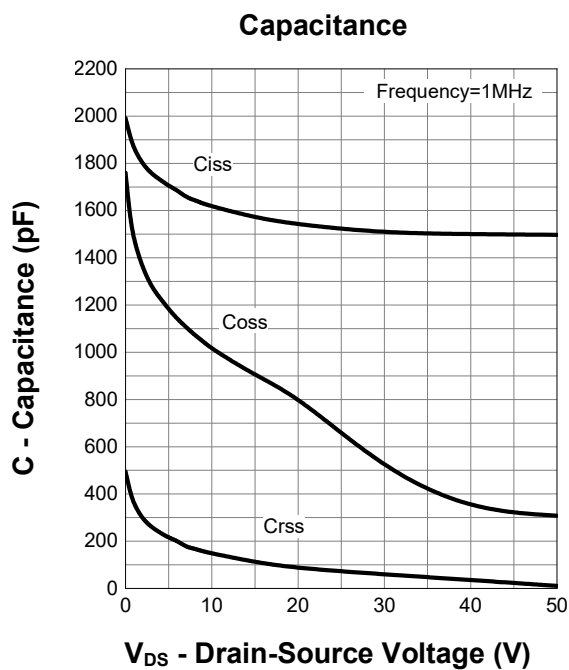
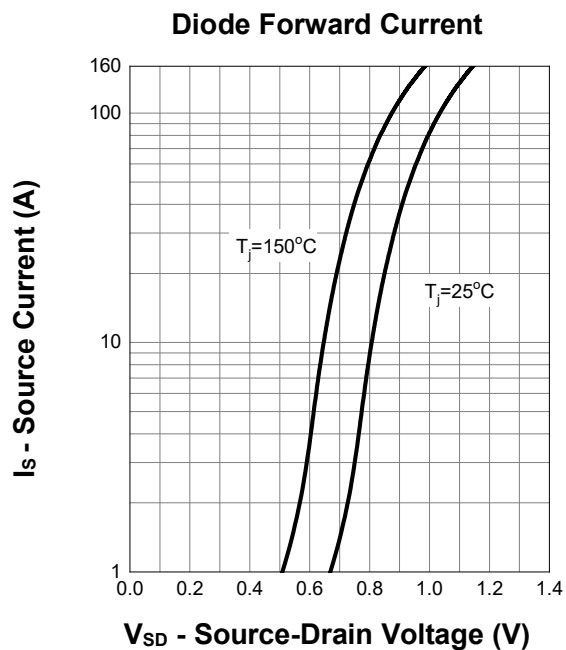
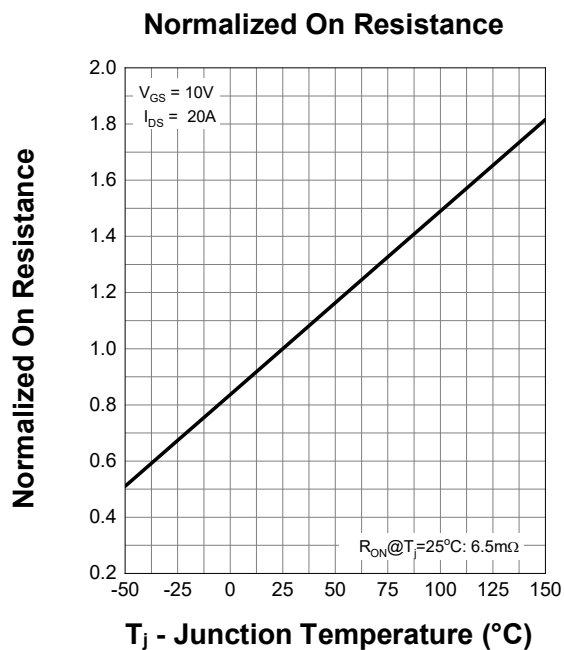
Transfer Characteristics



Normalized Threshold Voltage



7. Typical Characteristics (Cont.)



8. Package Dimensions

PDFN3.3x3.3-8L Package

